



BUK7277-55A

N-channel TrenchMOS standard level FET

12 June 2014

Product data sheet

1. General description

Standard level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product has been designed and qualified to the appropriate AEC standard for use in automotive critical applications.

2. Features and benefits

- AEC Q101 compliant
- Low conduction losses due to low on-state resistance
- Suitable for standard level gate drive sources
- Suitable for thermally demanding environments due to 175 °C rating

3. Applications

- 12 V and 24 V loads
- Automotive and general purpose power switching
- Motors, lamps and solenoids

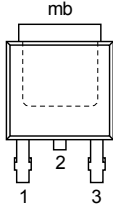
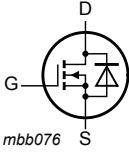
4. Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|----------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------|-----|-----|-----|------------|
| V_{DS} | drain-source voltage | $T_j \geq 25\text{ °C}; T_j \leq 175\text{ °C}$ | - | - | 55 | V |
| I_D | drain current | $V_{GS} = 10\text{ V}; T_{mb} = 25\text{ °C};$ Fig. 2 ; Fig. 3 | - | - | 18 | A |
| P_{tot} | total power dissipation | $T_{mb} = 25\text{ °C};$ Fig. 1 | - | - | 51 | W |
| Static characteristics | | | | | | |
| $R_{DS(on)}$ | drain-source on-state resistance | $V_{GS} = 10\text{ V}; I_D = 10\text{ A}; T_j = 175\text{ °C};$ Fig. 12 ; Fig. 13 | - | - | 154 | m Ω |
| | | $V_{GS} = 10\text{ V}; I_D = 10\text{ A}; T_j = 25\text{ °C};$ Fig. 12 ; Fig. 13 | - | 65 | 77 | m Ω |
| Avalanche ruggedness | | | | | | |
| $E_{DS(AL)S}$ | non-repetitive drain-source avalanche energy | $I_D = 6\text{ A}; V_{sup} \leq 55\text{ V}; R_{GS} = 50\text{ }\Omega;$ $V_{GS} = 10\text{ V}; T_{j(init)} = 25\text{ °C};$ unclamped | - | - | 36 | mJ |

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-----------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------|
| 1 | G | gate |  <p style="text-align: center;">DPAK (SOT428)</p> |  |
| 2 | D | drain | | |
| 3 | S | source | | |
| mb | D | mounting base; connected to drain | | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|-------------|---------|---------------------------------------------------------------------------------|---------|
| | Name | Description | Version |
| BUK7277-55A | DPAK | plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped) | SOT428 |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| BUK7277-55A | BUK7277-55A |

8. Limiting values

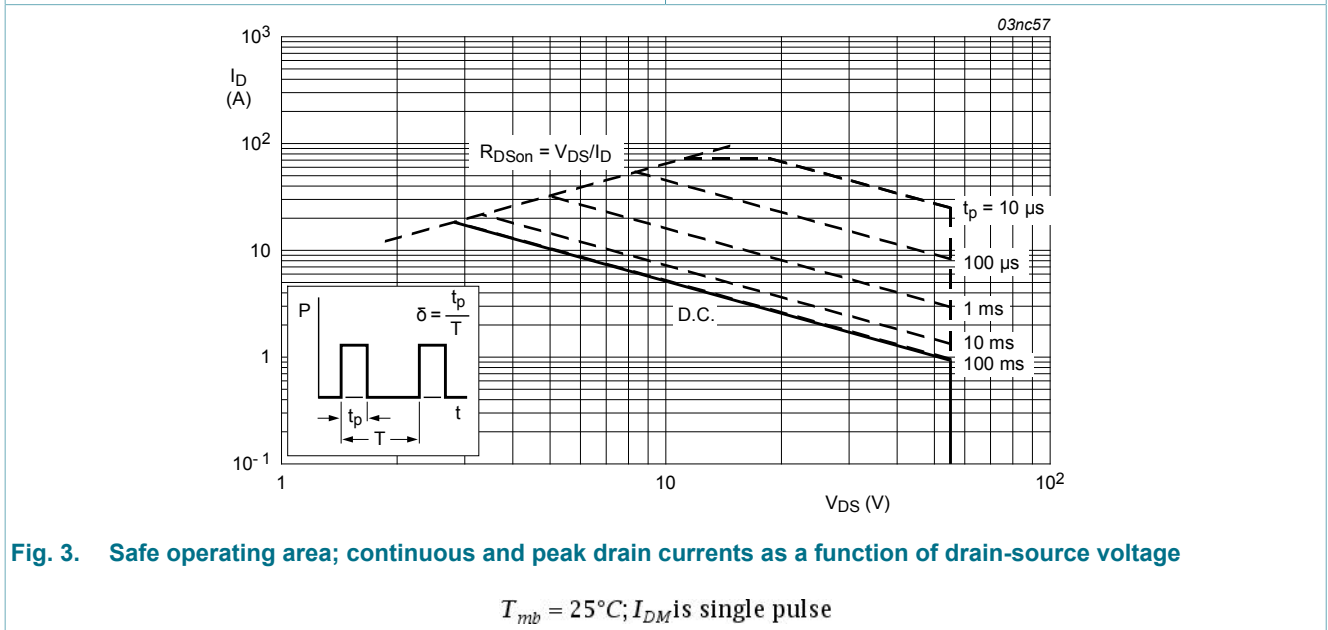
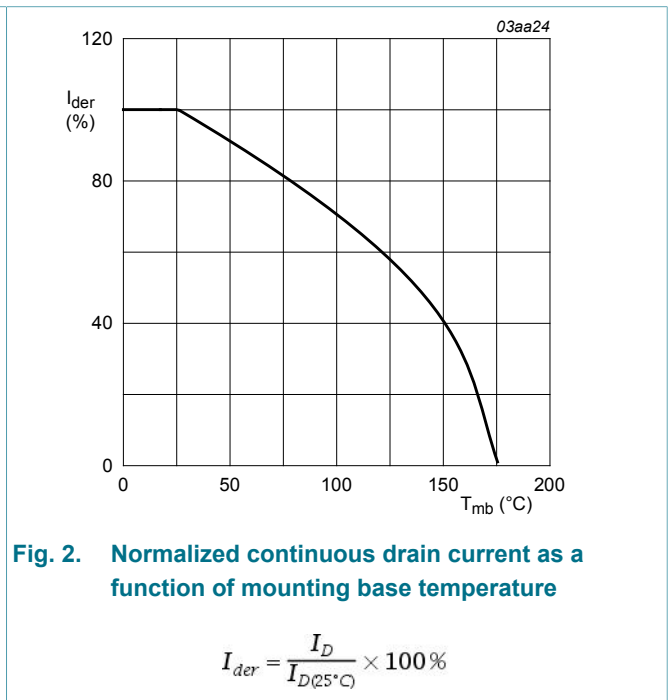
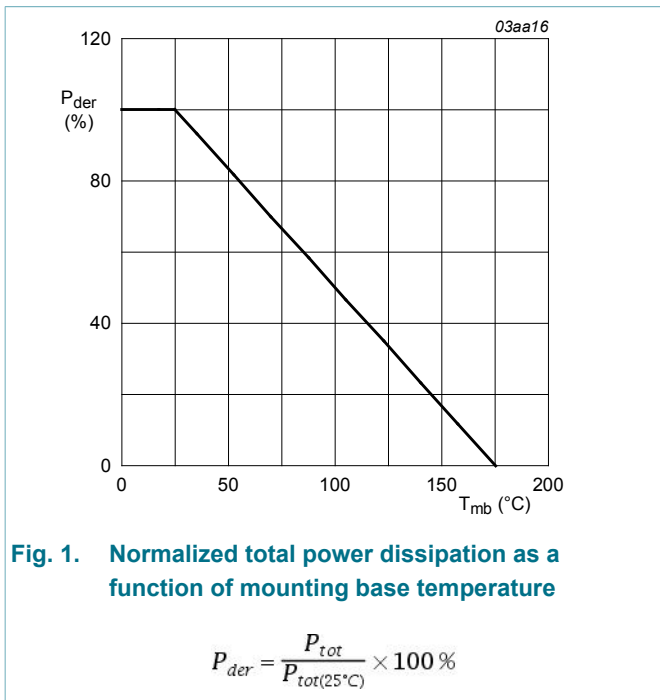
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|-------------------------|----------------------------------------------------------------------------------------------------|-----|-----|------|
| V_{DS} | drain-source voltage | $T_j \geq 25\text{ °C}$; $T_j \leq 175\text{ °C}$ | - | 55 | V |
| V_{DGR} | drain-gate voltage | $R_{GS} = 20\text{ k}\Omega$ | - | 55 | V |
| V_{GS} | gate-source voltage | | -20 | 20 | V |
| P_{tot} | total power dissipation | $T_{mb} = 25\text{ °C}$; Fig. 1 | - | 51 | W |
| I_D | drain current | $T_{mb} = 100\text{ °C}$; $V_{GS} = 10\text{ V}$; Fig. 2 | - | 13 | A |
| | | $T_{mb} = 25\text{ °C}$; $V_{GS} = 10\text{ V}$; Fig. 2 ; Fig. 3 | - | 18 | A |
| I_{DM} | peak drain current | $T_{mb} = 25\text{ °C}$; pulsed; $t_p \leq 10\text{ }\mu\text{s}$; Fig. 3 | [1] | 73 | A |
| T_{stg} | storage temperature | | -55 | 175 | °C |
| T_j | junction temperature | | -55 | 175 | °C |

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------------------------|----------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----|-----|------|
| Source-drain diode | | | | | |
| I_S | source current | $T_{mb} = 25\text{ }^\circ\text{C}$ | - | 18 | A |
| I_{SM} | peak source current | pulsed; $t_p \leq 10\text{ }\mu\text{s}$; $T_{mb} = 25\text{ }^\circ\text{C}$ | - | 73 | A |
| Avalanche ruggedness | | | | | |
| $E_{DS(AL)S}$ | non-repetitive drain-source avalanche energy | $I_D = 6\text{ A}$; $V_{sup} \leq 55\text{ V}$; $R_{GS} = 50\text{ }\Omega$; $V_{GS} = 10\text{ V}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; unclamped | - | 36 | mJ |

[1] Peak drain current is limited by chip, not package.



9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|---------------------------------------------------|------------------------------|-----|------|-----|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base | Fig. 4 | - | - | 2.9 | K/W |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | minimum footprint; FR4 board | - | 71.4 | - | K/W |

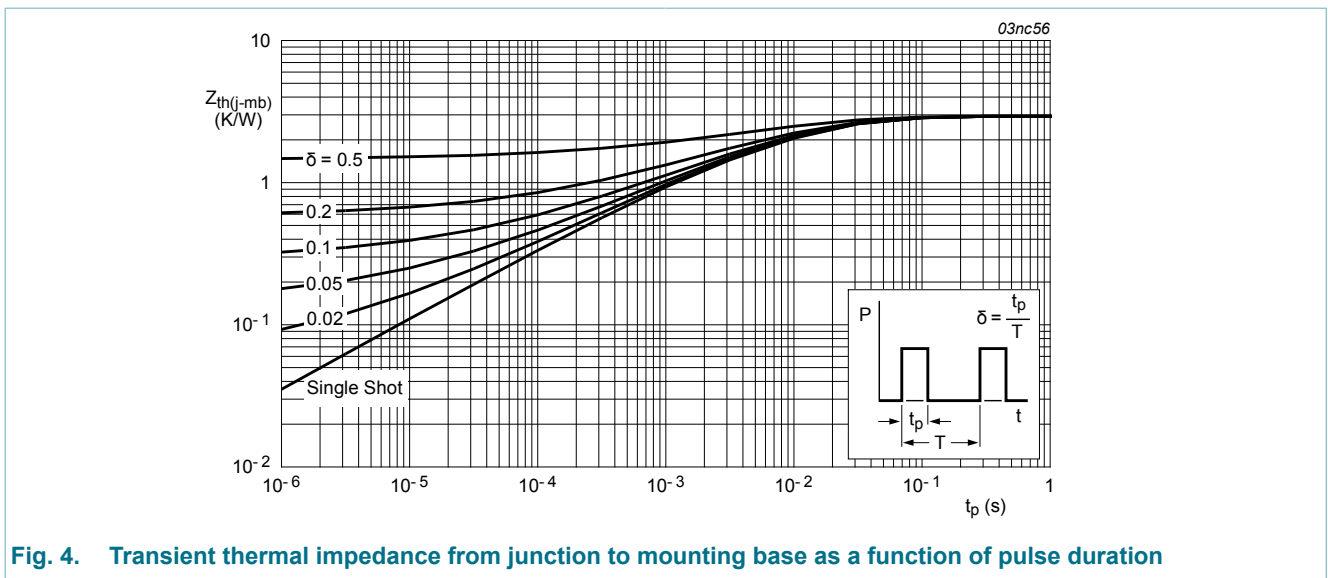


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|--------------------------------|-----------------------------------------------------------------------------------------------------|-----|------|-----|---------------|
| Static characteristics | | | | | | |
| $V_{(BR)DSS}$ | drain-source breakdown voltage | $I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | 55 | - | - | V |
| | | $I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = -55 \text{ }^\circ\text{C}$ | 50 | - | - | V |
| $V_{GS(th)}$ | gate-source threshold voltage | $I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ\text{C};$ Fig. 11 | 2 | 3 | 4 | V |
| | | $I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ }^\circ\text{C};$ Fig. 11 | - | - | 4.4 | V |
| | | $I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 175 \text{ }^\circ\text{C};$ Fig. 11 | 1 | - | - | V |
| I_{DSS} | drain leakage current | $V_{DS} = 55 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 0.05 | 10 | μA |
| | | $V_{DS} = 55 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 175 \text{ }^\circ\text{C}$ | - | - | 500 | μA |

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|----------------------------------|------------------------------------------------------------------------------------------------------------------------------------|-----|------|-----|------|
| I _{GSS} | gate leakage current | V _{GS} = 20 V; V _{DS} = 0 V; T _j = 25 °C | - | 2 | 100 | nA |
| | | V _{GS} = -20 V; V _{DS} = 0 V; T _j = 25 °C | - | 2 | 100 | nA |
| R _{DSon} | drain-source on-state resistance | V _{GS} = 10 V; I _D = 10 A; T _j = 175 °C; Fig. 12 ; Fig. 13 | - | - | 154 | mΩ |
| | | V _{GS} = 10 V; I _D = 10 A; T _j = 25 °C; Fig. 12 ; Fig. 13 | - | 65 | 77 | mΩ |
| Dynamic characteristics | | | | | | |
| C _{iss} | input capacitance | V _{GS} = 0 V; V _{DS} = 25 V; f = 1 MHz; T _j = 25 °C; Fig. 14 | - | 316 | 422 | pF |
| C _{oss} | output capacitance | | - | 92 | 110 | pF |
| C _{rss} | reverse transfer capacitance | | - | 64 | 87 | pF |
| t _{d(on)} | turn-on delay time | V _{DS} = 30 V; R _L = 1.2 Ω; V _{GS} = 10 V; R _{G(ext)} = 10 Ω; T _j = 25 °C | - | 10 | - | ns |
| t _r | rise time | | - | 50 | - | ns |
| t _{d(off)} | turn-off delay time | | - | 70 | - | ns |
| t _f | fall time | | - | 40 | - | ns |
| L _D | internal drain inductance | measured from drain lead from package to centre of die; T _j = 25 °C | - | 2.5 | - | nH |
| L _S | internal source inductance | measured from source lead from package to source bond pad; T _j = 25 °C | - | 7.5 | - | nH |
| Source-drain diode | | | | | | |
| V _{SD} | source-drain voltage | I _S = 10 A; V _{GS} = 0 V; T _j = 25 °C; Fig. 15 | - | 0.85 | 1.2 | V |
| t _{rr} | reverse recovery time | I _S = 20 A; dI _S /dt = -100 A/μs; V _{GS} = -10 V; V _{DS} = 30 V; T _j = 25 °C | - | 32 | - | ns |
| Q _r | recovered charge | | - | 120 | - | nC |

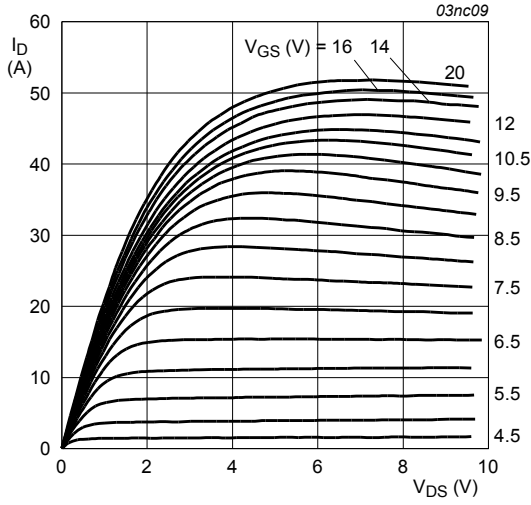


Fig. 5. Output characteristics; drain current as a function of drain-source voltage; typical values

$T_j = 25^\circ\text{C}$

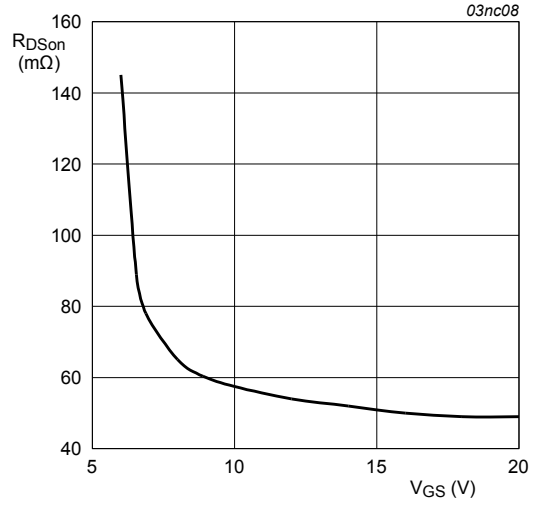


Fig. 6. Drain-source on-state resistance as a function of gate-source voltage; typical values

$T_j = 25^\circ\text{C}; I_D = 10\text{A}$

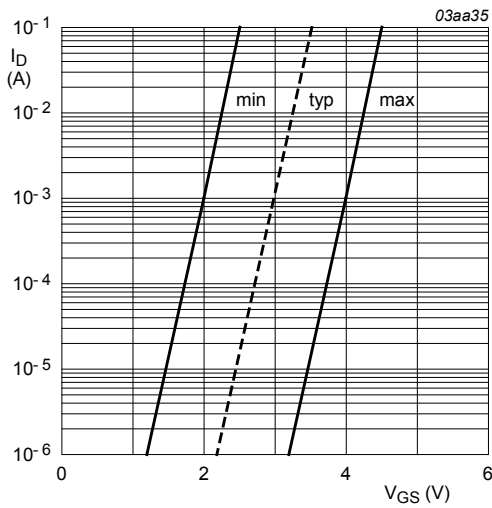


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

$T_j = 25^\circ\text{C}; V_{DS} = 5\text{V}$

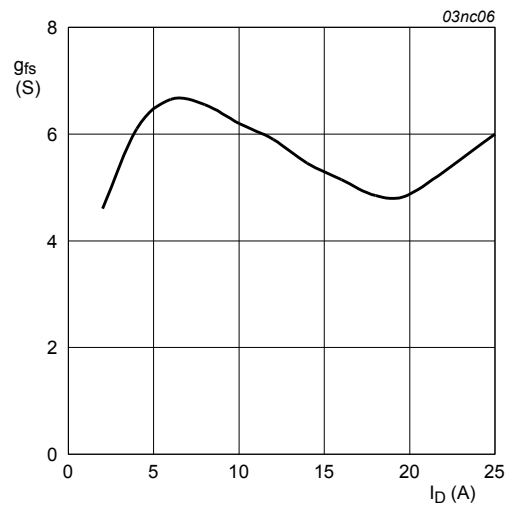


Fig. 8. Forward transconductance as a function of drain current; typical values

$T_j = 25^\circ\text{C}; V_{DS} = 25\text{V}$

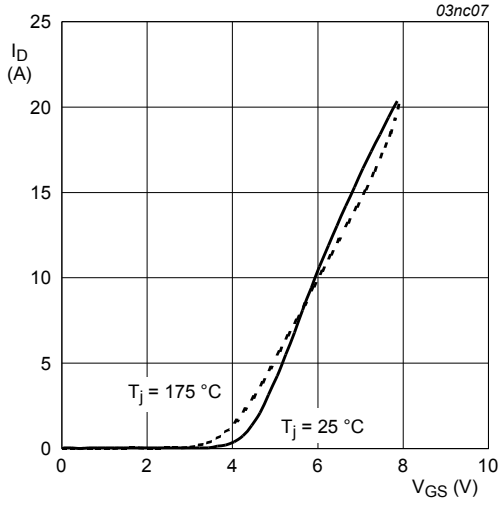


Fig. 9. Transfer characteristics: drain current as a function of gate-source voltage; typical values

$$V_{DS} = 25V$$

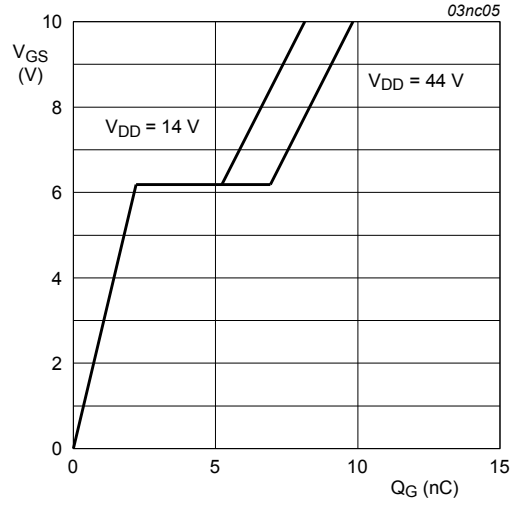


Fig. 10. Gate-source voltage as a function of gate charge; typical values

$$T_j = 25^{\circ}C; I_D = 10A$$

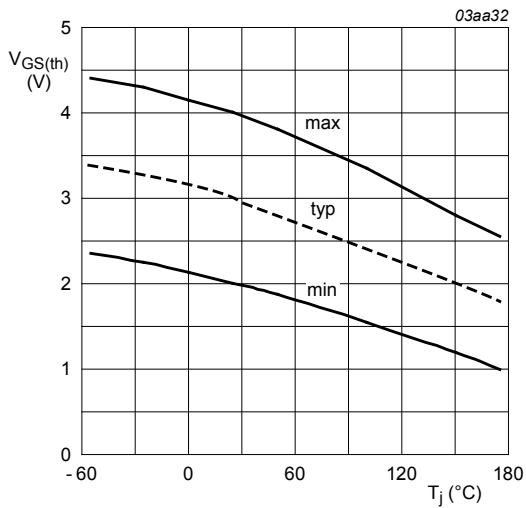


Fig. 11. Gate-source threshold voltage as a function of junction temperature

$$I_D = 1mA; V_{DS} = V_{GS}$$

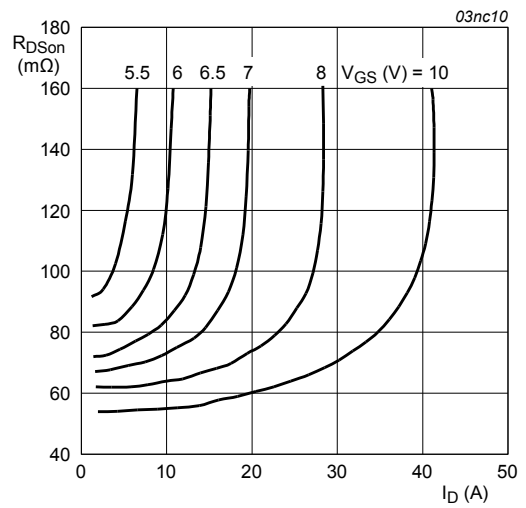


Fig. 12. Drain-source on-state resistance as a function of drain current; typical values

$$T_j = 25^{\circ}C$$

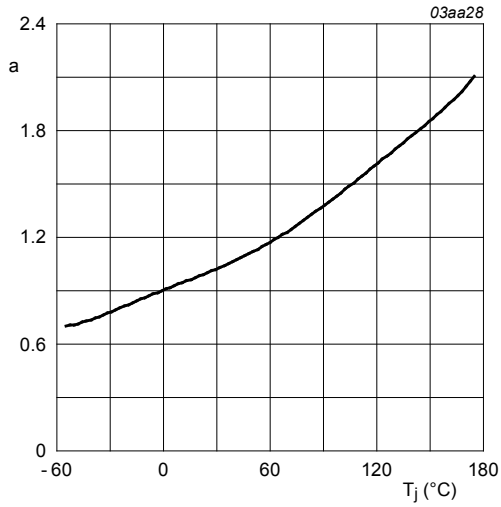


Fig. 13. Normalized drain-source on-state resistance factor as a function of junction temperature

$$a = \frac{R_{DSon}}{R_{DSon(25^{\circ}C)}}$$

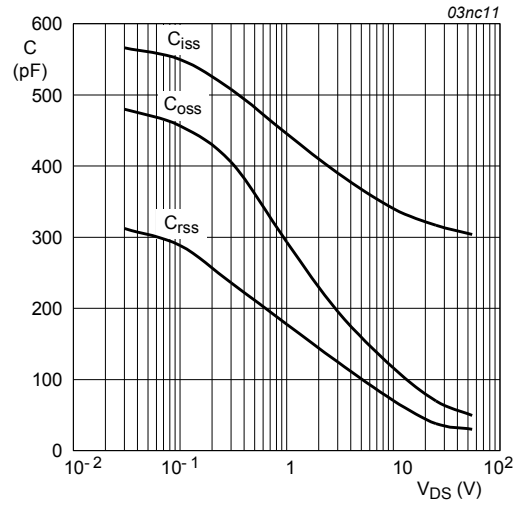


Fig. 14. Input, output and reverse capacitances as a function of drain-source voltage; typical values

$$V_{GS} = 0V; f = 1MHz$$

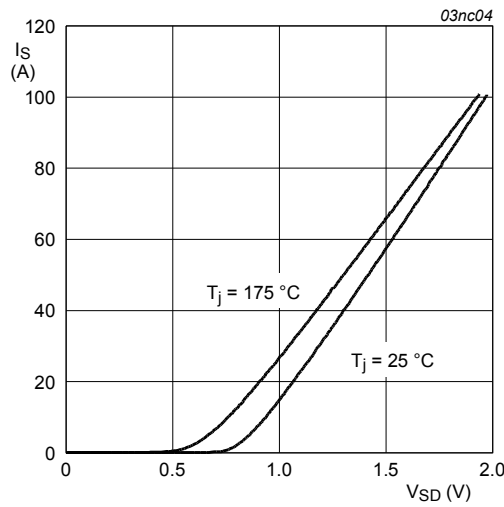
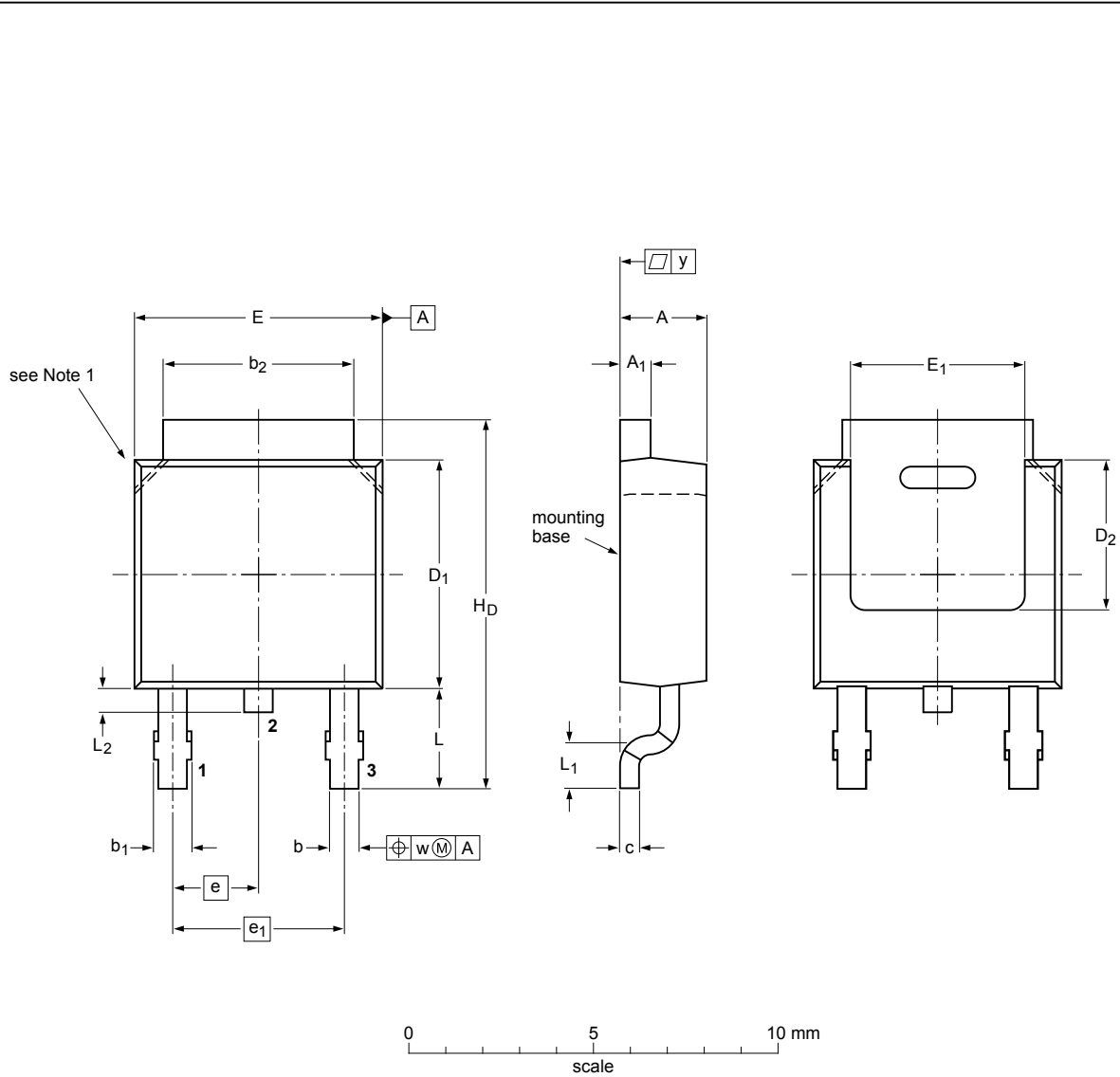


Fig. 15. Reverse diode current as a function of reverse diode voltage; typical values

$$V_{GS} = 0V$$

11. Package outline

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped) SOT428



Dimensions (mm are the original dimensions)

| Unit | A | A ₁ | b | b ₁ | b ₂ | c | D ₁ | D ₂ | E | E ₁ | e | e ₁ | H _D | L | L ₁ | L ₂ | w | y |
|------|------|----------------|------|----------------|----------------|------|----------------|----------------|------|----------------|-------|----------------|----------------|------|----------------|----------------|-----|-----|
| max | 2.38 | 0.93 | 0.89 | 1.1 | 5.46 | 0.56 | 6.22 | | 6.73 | | | | 10.4 | 2.95 | | 0.9 | | 0.2 |
| nom | | | | | | | | | | | 2.285 | 4.57 | | | | | 0.2 | |
| min | 2.22 | 0.46 | 0.71 | 0.9 | 5.00 | 0.20 | 5.98 | 4.0 | 6.47 | 4.45 | | | 9.6 | 2.55 | 0.5 | 0.5 | | |

Note

1. Plastic body may have 45° chamfer.

sot428_po

| Outline version | References | | | European projection | Issue date |
|-----------------|------------|--------|-------|---------------------|----------------------|
| | IEC | JEDEC | JEITA | | |
| SOT428 | | TO-252 | SC-63 | | 06-03-16 14-06-10 |

Fig. 16. Package outline DPAK (SOT428)

12. Legal information

12.1 Data sheet status

| Document status [1][2] | Product status [3] | Definition |
|--------------------------------|--------------------|---------------------------------------------------------------------------------------|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
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